### 505267853 01/08/2019

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5314625

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

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Name	Execution Date
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## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16242555

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ATTORNEY DOCKET NUMBER:	YOR920161634US02 (1605 C)	
NAME OF SUBMITTER:	JAMES J. BITETTO	
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DATE SIGNED:	01/08/2019	

#### **Total Attachments: 3**

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PATENT 505267853 REEL: 047932 FRAME: 0522

DOCKET NUMBER: YOR920161634US1 (163-1605)

#### ASSIGNMENT

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

and further identified by the Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having:

Title of the Invention: BORON SEGREGATION IN MAGNETIC TUNNEL JUNCTIONS

Serial Number: (insert series code and serial number here if/when available)

Whereas, Samsung Electronics, Co., Ltd. 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do 443-742, Republic of Korea, a South Korea corporation, located at (herein referred to as "Samsung Electronics"), desires to acquire, and each undersigned Inventor desires to grant to Samsung Electronics, the entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to Samsung Electronics (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to Samsung Electronics, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by Samsung Electronics, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in , its successors, legal representatives, and assigns, whenever requested by Samsung Electronics, its successors, legal representatives, or assigns.

Each undersigned Inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to Samsung Electronics and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned Inventor also hereby grants Samsung Electronics, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent application Serial Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

[Inventor Signature Pages Follow]

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# DOCKET NUMBER: YOR9201601634US1 (163-1605)

Executed by Inventor 1 of 2

Signature:

(Younghyun Kim)

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DOCKET NUMBER: YOR9201601634US1 (163-1605)

## Executed by Inventor 2 of 2

Signature: Date: 03/03/19

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